JSCJ

Reliability Report

Report NO.: M-R00036

1. Product Information

Supplier: JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number:	CJB110SN10
Package Type:	TO-263-2L
Part Description:	SMD/MOSFET
Report Date:	April-2025

2. Reliability Test Results: PASS

Test Item	Test Condition	Duration	Fail Quantity / S.S
Pre-and post-stress Electrical test	Ta=25℃	—	All parts
PC Precondition(For SMD Package Only)	JESD22-A113F/J-STD-020 1.Bake:125℃ 2.Soak: 85℃85%RH,168Hours MSL1 or 30℃60%RH,192Hours MSL3 3.Reflow 3Cycles Max 260℃ 4.all samples E-Test	>168Hours or >192Hours	0 / 308*3
TCT Temperature Cycling Test	JESD22 -A104 -55℃/15min 150℃/15min	1000Cycles	0 / 77*3
AC Autoclave	JESD22-A102 121℃, 100%RH	96Hours	0 / 77*3
UHAST Unbaised Highly Accelerated Stress Test	JESD22-A118 130℃, 85%RH	96Hours	—
THT High Humidity &Temp. Test	JESD22-A101 85℃ 85%RH	1000Hours	0 / 77*3
HTST High Temperature Storage Test	JESD22 -A103 T=Tstg max	1000Hours	0 / 77*3
H3TRB High Humidity &Temp. Bias Test	JESD22-A101 85℃ 85%RH VDS*80% VDS≦100V Max	1000Hours	—
HAST Highly Accelerated Stress Test	JESD22-A110 130℃ 85%RH VDS*80% VDS≦42V Max	96Hours	0 / 77*3
HTRB High Temperature Revers Bias Test	JESD22 -A108 Tj(max), VDS*80%	1000Hours	0 / 77*3
HTGB High Temperature Gate Bias Test	JESD22 -A108 Tj(max), VGS*100%	1000Hours	0 / 77*3
IOL Intermittent Operational Life	MIL-STD-750D Method 1037 △Tj≥100℃, On/Off:2min	15000Cycles	0 / 77*3
RSH Resistance to Solder Heat test	JESD22-A111B 260℃±5℃, 10(+2,-0)Seconds	—	0 / 30*3
SD Solderability	J-STD-002 1.Steam aging: 93℃ 8Hours 2.245℃ 3~5s	—	0 / 10*3

Notes:

1. Either H3TRB or HAST for reliability test.
2. Either AC or UHAST for reliability test.
3. Detailed MSL of the product refers to the MSL Report.

Remark: JSCJ Laboratory reserves the right of final interpretation of this report